

November 1, 2018

Increase in Productive Capacity of IC Package Substrate toward Next Generation and New Markets

We have decided to make a capital investment aiming to enhance productive capacity of IC package substrate in order to respond to the new demand centering on high-performance and high-speed semiconductors and servers, and image processing as in the outline given below:

Semiconductor market is expected to expand more with development of IoT, AI and devices for vehicles as well as increasing demand of high-speed and high-capacity servers such as data center. We aim to establish a solid position in the IC package substrate market, which results in stable growth of our Electronics business so that we will achieve the medium-term management plan keeping up with new demands steadily.

< Outline of Facility Investment Plan >

- (1) Investment : Production facilities for IC package substrate toward the next-generation products and the new markets
- (2) Investment Value : 70 billion yen consolidated between FY2019 and FY2021
- (3) Installation Site : The Second Building at Ogaki Central Plant and Ogaki Plant in Ogaki City, Gifu Pref.
- (4) Period of Operation : We plan to come online sequentially in FY2019 and start commercial production in FY2020.
- (5) Productive Capacity : The plan enables us to increase the productive capacity of IC package substrate by about 50% (layer conversion) including the contribution from the prior investment by FY2021.



The Second Building at Ogaki Central Plant



Ogaki Plant